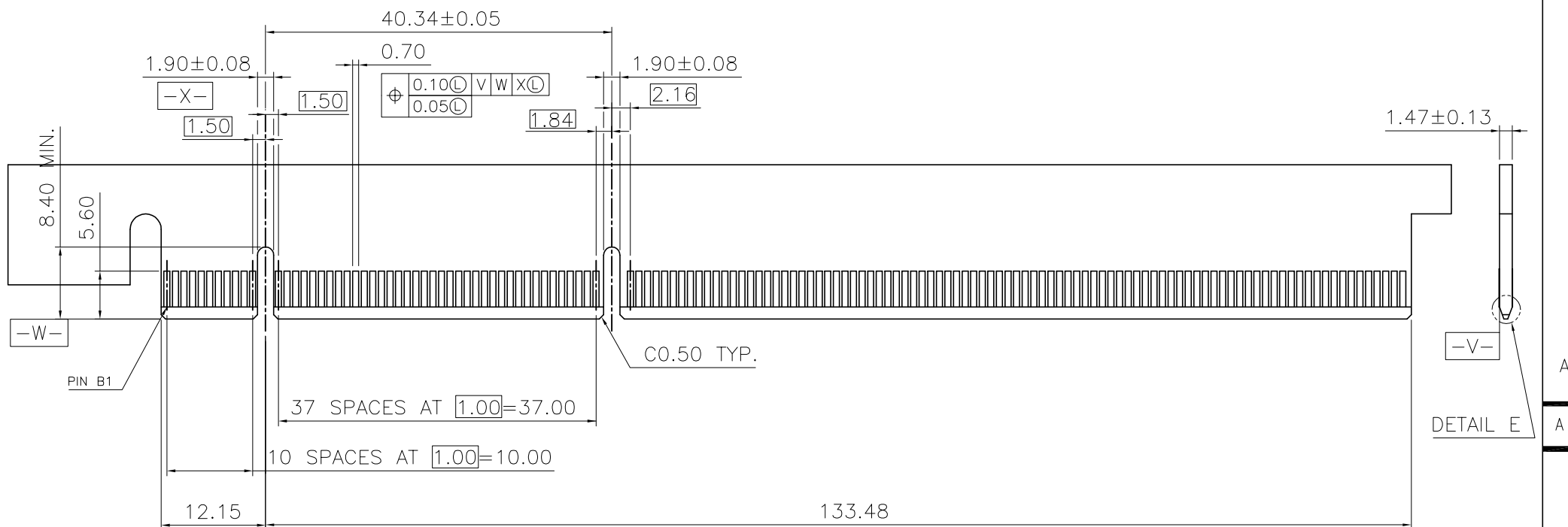
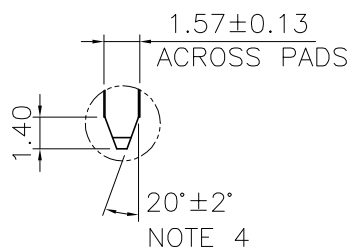


4

[illegible]



DAUGHTER CARD PRIMARY (COMPONENT) SIDE



SCALE 2:1
DETAIL E

mat'l. code				surface	tolerance	projection	product family		
-				-	ASME_Y14.5	⌀	PCI_EXPRESS		
lfr	ecn no	dr	date	tolerances unless otherwise specified		MM	title		
				angles	.0±0.30		PCI_EXPRESS_SUPER_SLOT_GEN3		
				±2'	.00±0.20	scale N/A	CARD_EDGE_TH_280P_ASS'Y		
				dr	STONE_LI	2015-05-27	dwg no		
				engr	STONE_LI	2015-05-27	sheet 3 of 4		
				chr	/	2015-05-27	10037901		
				appd	PM_ZHENG	2015-05-27	type		
sheet index				revision	E		CUSTOMER Drawing		
				sheet					

NOTES:

1.MATERIAL:

HOUSING: HIGH TEMPERATURE NYLON, GLASS FILLED UL94V-0
RATED. SUITABLE FOR IR REFLOW.

TERMINAL: COPPER ALLOY

PLATING: 50u" NICKEL UNDERPLATE ALL OVER
CONTACT AREA PLATING - SEE PRODUCT NUMBER CODE
SOLDER TAIL: TIN OR TIN/LEAD (90/10) - SEE PRODUCT
NUMBER CODE 100u" MIN. OVER 50u" NICKEL

METAL BOARD LOCKS: COPPER ALLOY

FINISH: 100u" TIN OR TIN/LEAD (90/10) OVER 50u" NICKEL
UNDERPLATE SEE PRODUCT NUMBER CODE

2.PRODUCT SPECIFICATION: GS-12-233

③THE HORIZONTAL AXIS FOR THE HOLE PATTERN IS ESTABLISHED BY

A LINE THROUGH THE CENTER OF THE TWO Ø2.35 HOLES.

THE VERTICAL AXIS IS 90° TO THE HORIZONTAL AXIS, THROUGH THE CENTER
OF DATUM Z.

④CHAMFER EDGES MUST BE FREE OF CUTTING BURRS.

5.RoHS COMPATIBLE PRODUCT SPECIFICATIONS

a - PLATING:

- "LF" MEANS THE PRODUCT IS LEAD-FREE, 2um MINIMUM MATTE TIN OVER 1.27um
MINIMUM NICKEL UNDERPLATE.

b - MANUFACTURING PROCESS COMPATIBILITY

- THE HOUSING WILL WITHSTAND EXPOSURE TO 260°C±5°C SOLDER BATH TEMPERATURE FOR
5 SECONDS IN A REFLOW SOLDER APPLICATION WITH A 1.6mm MIN THICK CIRCUIT BOARD.

PRODUCT NUMBER CODE

10037901 -x x x x x □ □

HOUSING COLOR OPTIONS

1-BLACK

PEGS OPTIONS

1-METAL BOARD LOCKS

TERMINAL PLATING OPTIONS

0-50u" Ni UNDERPLATE
30u" Au CONTACT AREA
100u" TIN TAIL AREA ----- COMPATIBLE RoHS

1-50u" Ni UNDERPLATE
15u" Au CONTACT AREA
100u" TIN TAIL AREA ----- COMPATIBLE RoHS

2-50u" Ni UNDERPLATE
GOLD FLASH CONTACT AREA
100u" TIN TAIL AREA ----- COMPATIBLE RoHS

3-50u" Ni UNDERPLATE
30u" Au CONTACT AREA
100u" TIN/LEAD TAIL AREA ----- INCOMPLIANT RoHS

4-50u" Ni UNDERPLATE
15u" Au CONTACT AREA
100u" TIN/LEAD TAIL AREA ----- INCOMPLIANT RoHS

5-50u" Ni UNDERPLATE
GOLD FLASH CONTACT AREA
100u" TIN/LEAD TAIL AREA ----- INCOMPLIANT RoHS

LEAD FREE OPTION

LEAVE BLANK FOR TERMINAL PLATING 3,4,5
"LF" FOR TERMINAL PLATING OPTION 0,1,2

PACKAGING OPTIONS
T-TRAY PACKAGING

TAIL LENGTH OPTIONS

LATCHING OPTIONS
0-WITHOUT LATCHING

	DIM "D"	PCB THICKNESS	BOARD LOCKS DIM "G"
0	2.30 ± 0.25 -0.13	1.56±0.10	1.70±0.15
1	3.10 ± 0.25 -0.13	2.36±0.10	2.50±0.15
2	2.54±0.25	1.56±0.10	1.70±0.15

mat'l. code -				surface - ✓	tolerance ASME_Y14.5	projection 	product family PCI_EXPRESS	
lfr	ecn	no	dr	date	tolerances unless otherwise specified		title	
					angles	linear .0±0.30 .00±0.20 ±2' .000±0.10	PCI_EXPRESS_SUPER_SLOT_GEN3	
					dr	STONE_LI 2015-05-27	CARD_EDGE_TH_280P_ASS'Y	
					engr	STONE_LI 2015-05-27	dwg no	
					chr	/ 2015-05-27	sheet 4 of 4	
					appd	PM_ZHENG 2015-05-27	size	
sheet		revision	E				10037901	
index		sheet					A4	
							type	
							CUSTOMER Drawing	